U.S. PTO 12/290170 10/28/2008

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Form PTO-1595 (Rev. 09/ 04) OMB No. 0851-0027 (exp. 6/30/2005) RECORDATION FORM C PATENTS O 103534533 To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below. 2. Name and address of receiving party(les) 1. Name of conveying party(les)/Execution Date(s): AKIMITSU HIO SONY CORPORATION Internal Address: Street Address: Execution Date(s): October 2, 2008 1-7-1 Konan, Minato-ku X No Additional name(s) of conveying party(ies) attached? Tokyo 3. Nature of Conveyance: 108-0075 x Assignment Merger **JAPAN** Change of Name Security Agreement City: Government Interest Assignment State: Executive Order 9424, Confirmatory License Zip: Country: Additional name(s) & address(es) Yes X No Other attached: This document is being filed together with a new application. 4. Application or patent number(s): B. Patent No.(s) A. Patent Application No.(s) Additional numbers attached? Yes 6. Total number of applications and 5. Name and address to whom correspondence concerning document should be mailed: patents involved: Name: Dennis M. Smid, Esq. LERNER, DAVID, LITTENBERG, 40.00 KRUMHOLZ & MENTLIK, LLP 7. Total fee (37 CFR 1.21(h) & 3.41) Internal Address: Atty. Dkt.: SONYJP 3.0-1741 Authorized to be charged by credit card Street Address: 600 South Avenue West Authorized to be charged to deposit account **Enclosed** None required (government interest not affecting title) Westfield Citv: 8. Payment Information Zip: 07090 a. Credit Card Last 4 Numbers State: **Expiration Date** (908) 518-6374 Phone Number: _ (908) 654-0415 b. Deposit Account Number 12-1095 Fax Number: Authorized User Name Dennis M. Smid, Esq. dsmid@ldlkm.com Email Address: 9. Signature: 11/12/2008 DBYRNE

Signature Dennis M. Smid, Esq. - 34,930

Name of Person Signing

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Total number of pages including cover sheet, attachments, and documents:

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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION DISPLAY APPARATUS, INFORMATION DISPLAY METHOD, IMAGING APPARATUS, AND IMA DATA SENDING METHOD FOR USE WITH IMAGING APPARATUS for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my na and address; AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be grant therefor in the United States and in any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficience of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title a interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Lette Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Conventi Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of American adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue t said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to r and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said inventic applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and law! papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require a prepare at its own expense; And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documer relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known a accessible to me and will testify as to the same in any interference or litigation related thereto; And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into whi would conflict with this assignment and sale. And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date this application in the spaces that follow: Serial Number: ______ Filing Date: ______ This assignment executed on the dates indicated below. Akimitsu HIO Name of first or sole inventor Execution date of U.S. Patent Application Tokyo, Japan

Residence of first or sole inventor

Akimitsu Hio
Signature of first or sole inventor

RECORDED: 10/28/2008

PATENT

Date of this assignme

REEL: 021828 FRAME: 0859

Oct. 2, 2008